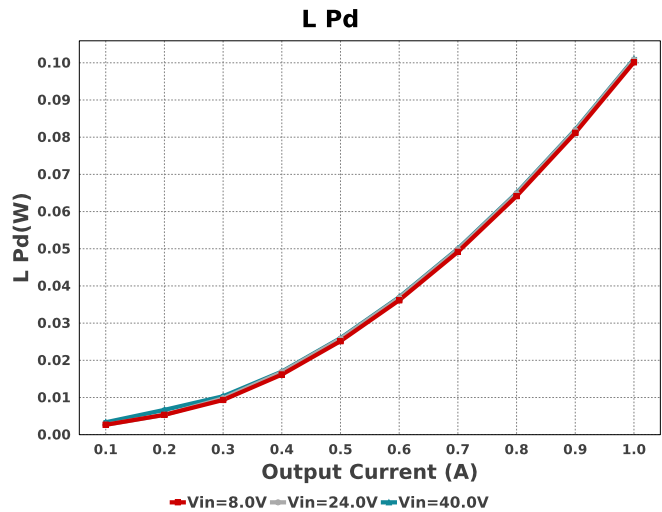
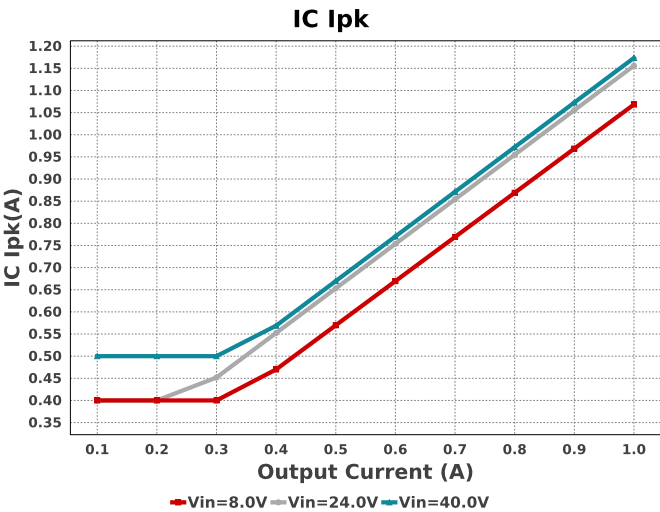
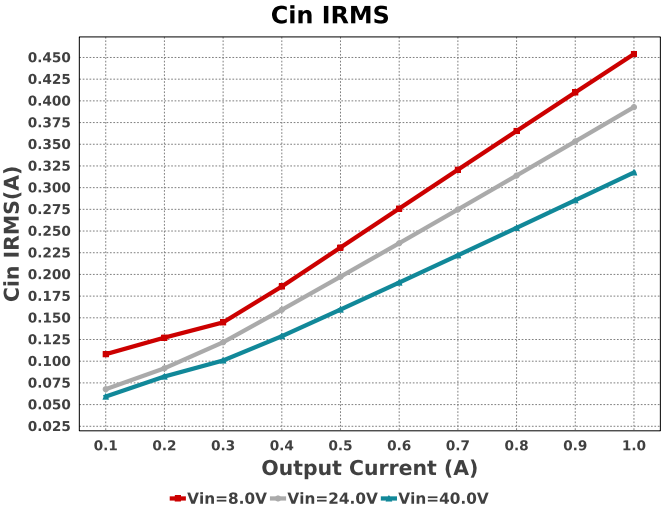
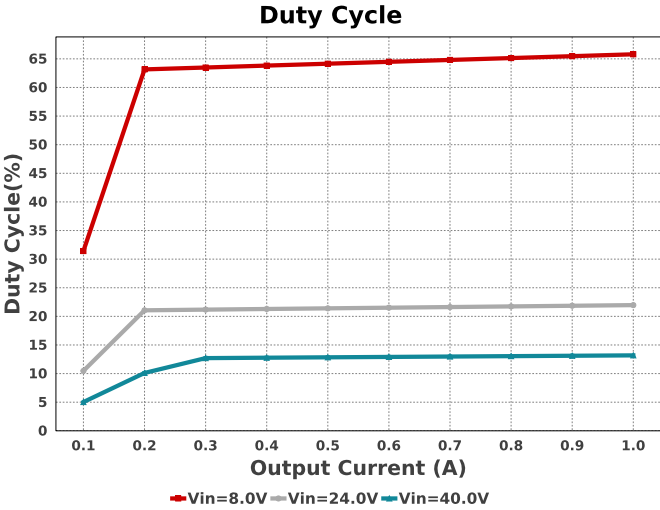
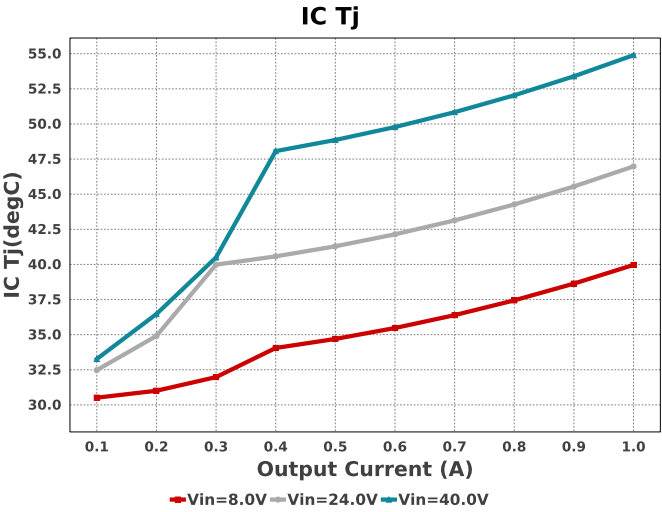
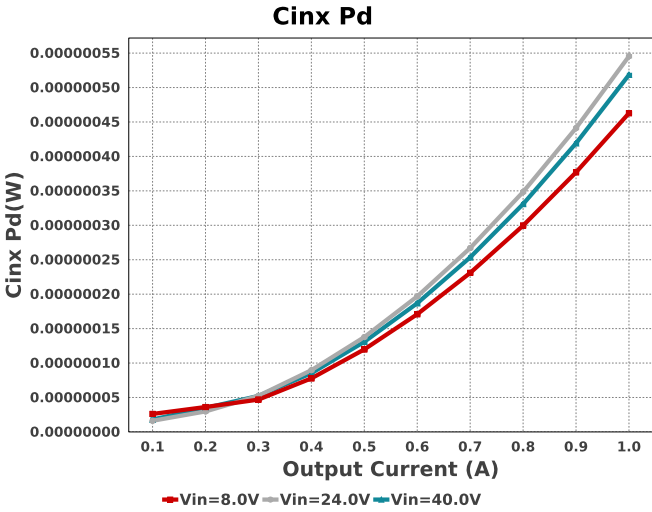
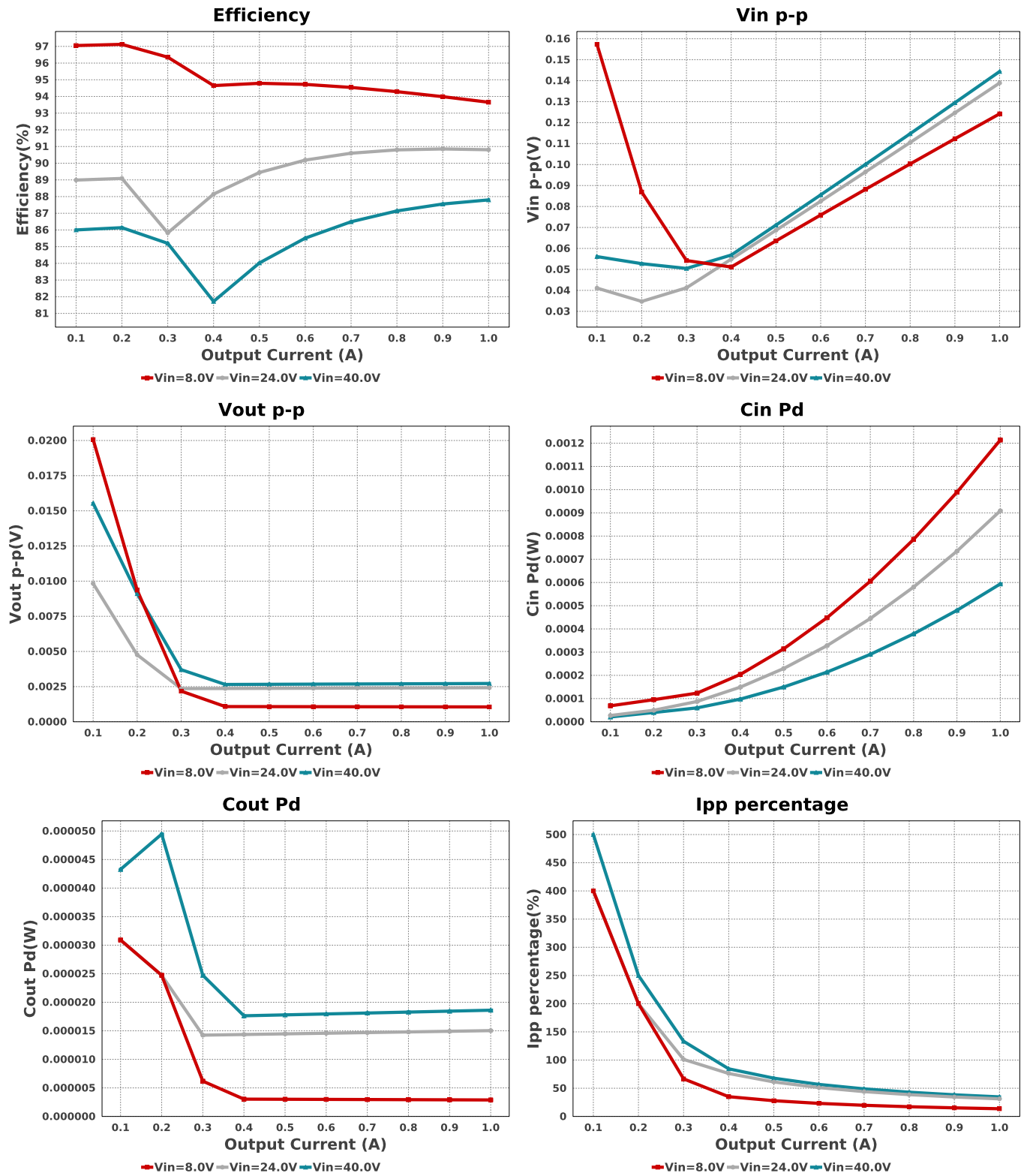


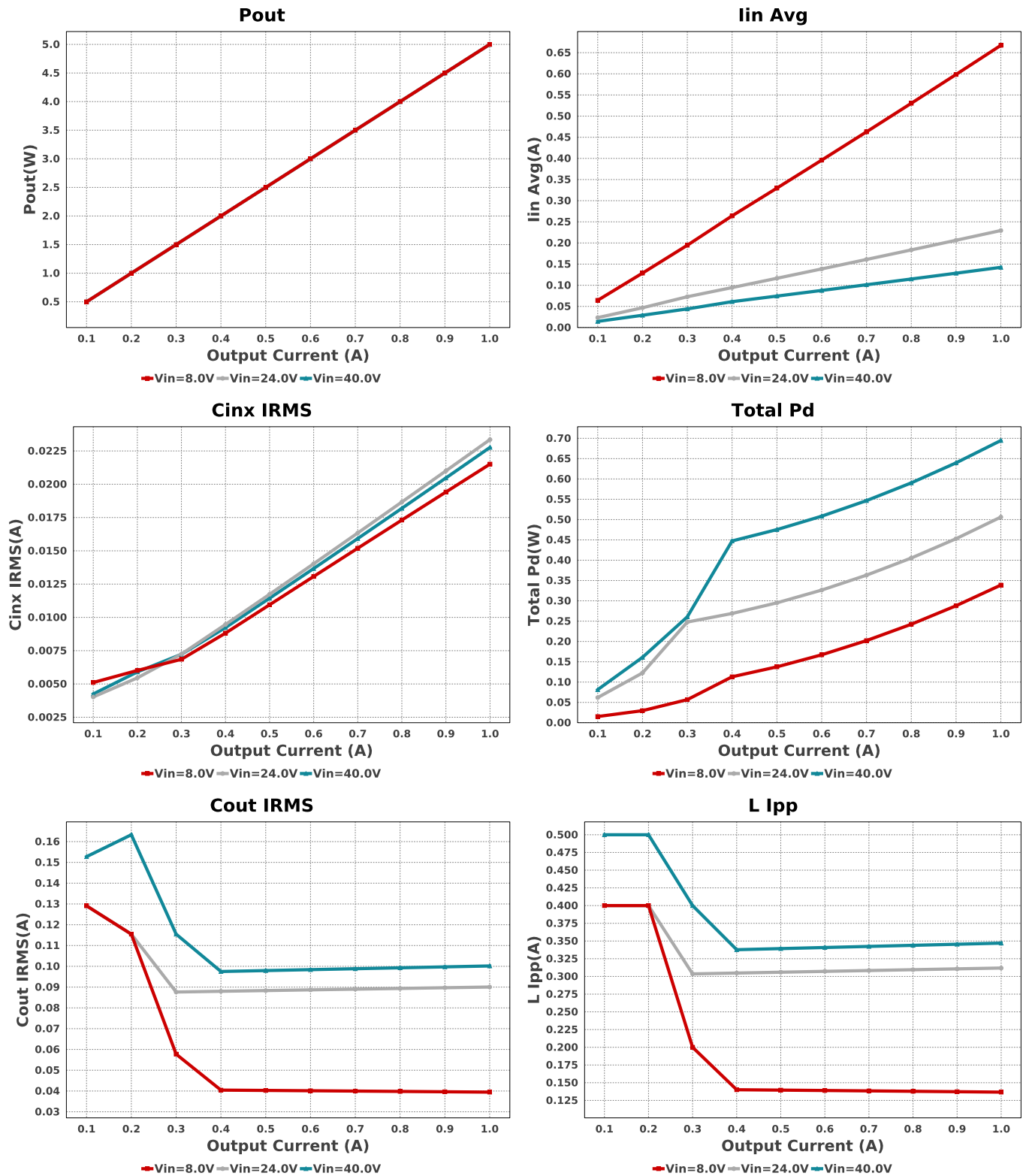


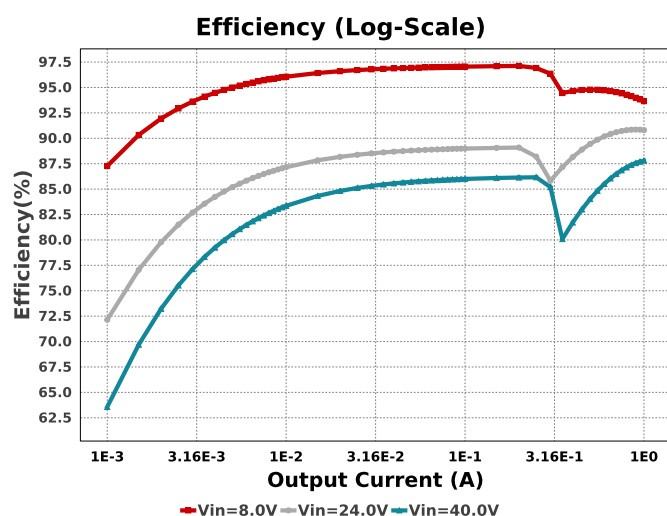
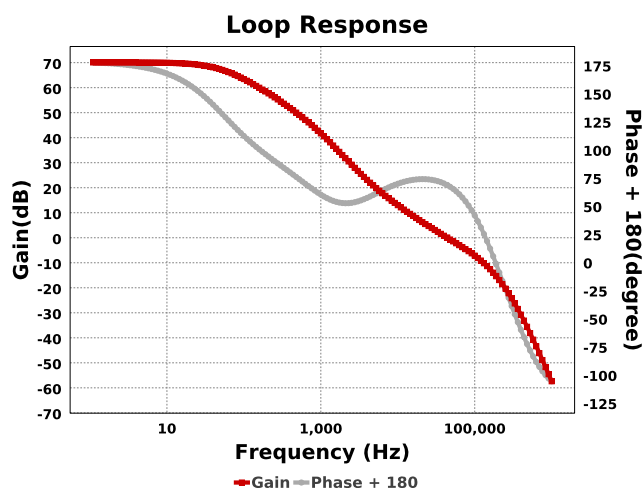
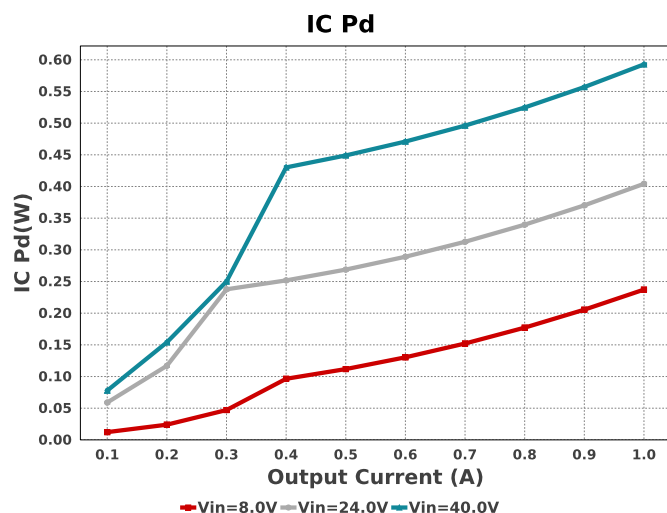
Device = LMR36510ADDAR
Topology = Buck
Created = 2025-09-02 05:40:32.404
BOM Cost = \$2.44
BOM Count = 12
Total Pd = 0.69W

Name	Manufacturer	Part Number	Properties	Qty	Price	Footprint
U1	Texas Instruments	LMR36510ADDAR	Switcher	1	\$0.94	 DDA0008J 55 mm ²









Operating Values

#	Name	Value	Category	Description
1.	Cin IRMS	317.502 mA	Capacitor	Input capacitor RMS ripple current
2.	Cin Pd	593.75 μ W	Capacitor	Input capacitor power dissipation
3.	Cinx IRMS	22.768 mA	Capacitor	Bulk capacitor RMS ripple current
4.	Cinx Pd	518.38 nW	Capacitor	Bulk capacitor power dissipation
5.	Cout IRMS	100.17 mA	Capacitor	Output capacitor RMS ripple current
6.	Cout Pd	18.608 μ W	Capacitor	Output capacitor power dissipation
7.	IC Ipk	1.173 A	IC	Peak switch current in IC
8.	IC Pd	592.8 mW	IC	IC power dissipation
9.	IC Tj	54.898 degC	IC	IC junction temperature
10.	IC Tolerance	15.0 mV	IC	IC Feedback Tolerance
11.	ICThetaJA Effective	42.0 degC/W	IC	Effective IC Junction-to-Ambient Thermal Resistance
12.	Iin Avg	142.37 mA	IC	Average input current
13.	Ipp percentage	34.7 %	Inductor	Inductor ripple current percentage (with respect to average inductor current)
14.	L Ipp	347.0 mA	Inductor	Peak-to-peak inductor ripple current
15.	L Pd	101.0 mW	Inductor	Inductor power dissipation
16.	Cin Pd	593.75 μ W	Power	Input capacitor power dissipation
17.	Cinx Pd	518.38 nW	Power	Bulk capacitor power dissipation
18.	Cout Pd	18.608 μ W	Power	Output capacitor power dissipation
19.	IC Pd	592.8 mW	Power	IC power dissipation
20.	L Pd	101.0 mW	Power	Inductor power dissipation
21.	Total Pd	694.652 mW	Power	Total Power Dissipation
22.	BOM Count	12	System Information	Total Design BOM count
23.	Cross Freq	43.957 kHz	System Information	Bode plot crossover frequency
24.	Duty Cycle	13.184 %	System Information	Duty cycle
25.	Efficiency	87.802 %	System Information	Steady state efficiency
26.	FootPrint	279.0 mm ²	System Information	Total Foot Print Area of BOM components

#	Name	Value	Category	Description
27.	Frequency	400.0 kHz	System Information	Switching frequency
28.	Gain Marg	-15.259 dB	System Information	Bode Plot Gain Margin
29.	Iout	1.0 A	System Information	Iout operating point
30.	Low Freq Gain	70.083 dB	System Information	Gain at 1Hz
31.	Mode	CCM	System Information	Conduction Mode
32.	Phase Marg	69.794 deg	System Information	Bode Plot Phase Margin
33.	Pout	5.0 W	System Information	Total output power
34.	Total BOM	\$2.44	System Information	Total BOM Cost
35.	Vin	40.0 V	System Information	Vin operating point
36.	Vin p-p	144.379 mV	System Information	Peak-to-peak input voltage
37.	Vout	5.0 V	System Information	Operational Output Voltage
38.	Vout Actual	5.016 V	System Information	Vout Actual calculated based on selected voltage divider resistors
39.	Vout Tolerance	3.142 %	System Information	Vout Tolerance based on IC Tolerance (no load) and voltage divider resistors if applicable
40.	Vout p-p	2.723 mV	System Information	Peak-to-peak output ripple voltage

Design Inputs

Name	Value	Description
Iout	1.0	Maximum Output Current
VinMax	40.0	Maximum input voltage
VinMin	8.0	Minimum input voltage
Vout	5.0	Output Voltage
base_pn	LMR36510A	Base Product Number
source	DC	Input Source Type
Ta	30.0	Ambient temperature

WEBENCH® Assembly

Component Testing

Some published data on components in datasheets such as Capacitor ESR and Inductor DC resistance is based on conservative values that will guarantee that the components always exceed the specification. For design purposes it is usually better to work with typical values. Since this data is not always available it is a good practice to measure the Capacitance and ESR values of C_{in} and C_{out} , and the inductance and DC resistance of L1 before assembly of the board. Any large discrepancies in values should be electrically simulated in WEBENCH to check for instabilities and thermally simulated in WebTHERM to make sure critical temperatures are not exceeded.

Soldering Component to Board

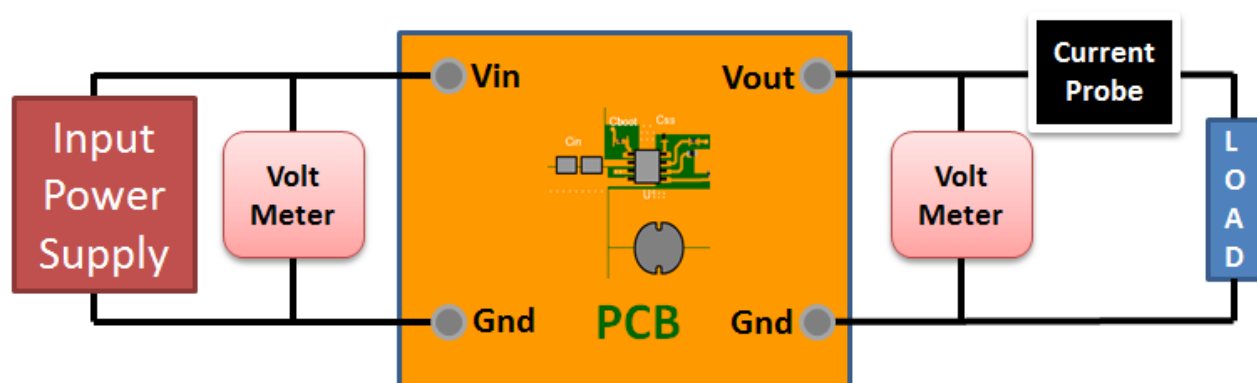
If board assembly is done in house it is best to tack down one terminal of a component on the board then solder the other terminal. For surface mount parts with large tabs, such as the DPAK, the tab on the back of the package should be pre-tinned with solder, then tacked into place by one of the pins. To solder the tab down to the board place the iron down on the board while resting against the tab, heating both surfaces simultaneously. Apply light pressure to the top of the plastic case until the solder flows around the part and the part is flush with the PCB. If the solder is not flowing around the board you may need a higher wattage iron (generally 25W to 30W is enough).

Initial Startup of Circuit

It is best to initially power up the board by setting the input supply voltage to the lowest operating input voltage 8.0V and set the input supply's current limit to zero. With the input supply off connect up the input supply to V_{in} and GND. Connect a digital volt meter and a load if needed to set the minimum load of the design from V_{out} and GND. Turn on the input supply and slowly turn up the current limit on the input supply. If the voltage starts to rise on the input supply continue increasing the input supply current limit while watching the output voltage. If the current increases on the input supply, but the voltage remains near zero, then there may be a short or a component misplaced on the board. Power down the board and visually inspect for solder bridges and recheck the diode and capacitor polarities. Once the power supply circuit is operational then more extensive testing may include full load testing, transient load and line tests to compare with simulation results.

Load Testing

The setup is the same as the initial startup, except that an additional digital voltmeter is connected between V_{in} and GND, a load is connected between V_{out} and GND and a current meter is connected in series between V_{out} and the load. The load must be able to handle at least rated output power + 50% (7.5 watts for this design). Ideally the load is supplied in the form of a variable load test unit. It can also be done in the form of suitably large power resistors. When using an oscilloscope to measure waveforms on the prototype board, the ground leads of the oscilloscope probes should be as short as possible and the area of the loop formed by the ground lead should be kept to a minimum. This will help reduce ground lead inductance and eliminate EMI noise that is not actually present in the circuit.

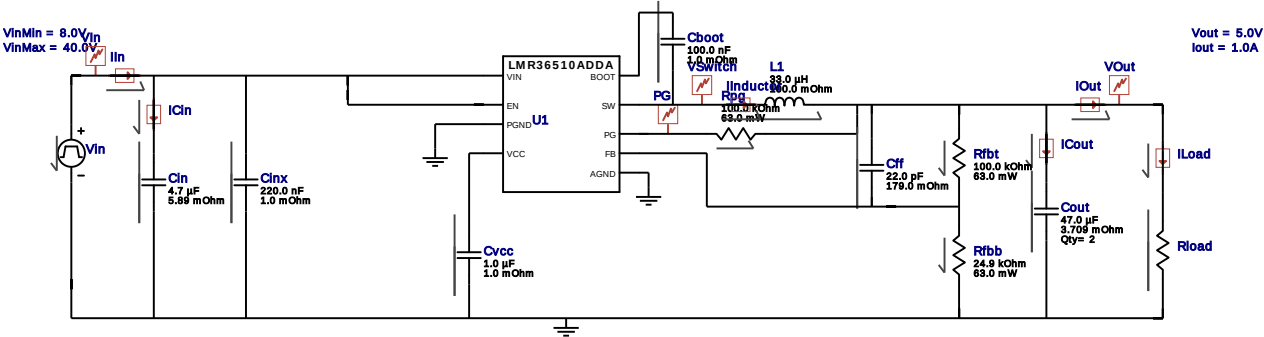


WEBENCH® Electrical Simulation Report

Design Id = 50

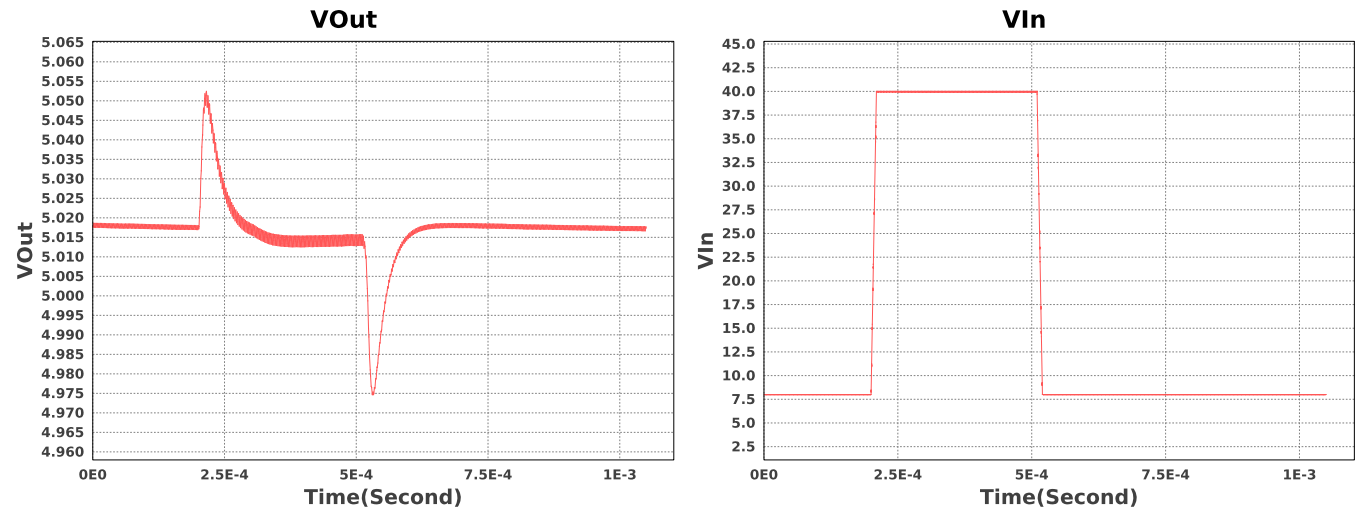
sim_id = 1

Simulation Type = Input Transient



Simulation Parameters

#	Name	Parameter Name	Description	Values
1.	L1	IC	Initial Current	1.0 A
2.	Rload	R	load resistance	5.0 ohm



Design Assistance

- Master key : 5863439BFAEDA59B[v1]
- LMR36510A Product Folder : <http://www.ti.com/product/LMR36510> : contains the data sheet and other resources.

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